



SLOVENSKI STANDARD

SIST EN 60286-3:2008

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SIST EN 60286-3:2002

Pakiranje komponent za avtomatsko ravnanje - 3. del: Pakiranje komponent za površinsko montažo na neprekinjenih trakovih (IEC 60286-3:2007)

Packaging of components for automatic handling - Part 3: Packaging of surface mount components on continuous tapes (IEC 60286-3:2007)

Gurtung und Magazinierung von Bauelementen für die automatische Verarbeitung - Teil 3: Gurtung von oberflächenmontierbaren Bauelementen auf Endlosgurten (IEC 60286-3:2007)

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Emballage de composants pour opérations automatisées - Partie 3: Emballage des composants appropriés au montage en surface en bandes continues (IEC 60286-3:2007)

Ta slovenski standard je istoveten z: EN 60286-3:2007

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31.020	Elektronske komponente na splošno	Electronic components in general
55.060	Tulci. Vretena	Spools. Bobbins

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en,de

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English version

**Packaging of components for automatic handling -
Part 3: Packaging of surface mount components on continuous tapes
(IEC 60286-3:2007)**

Emballage de composants
pour opérations automatisées -
Partie 3: Emballage des composants
appropriés au montage en surface
en bandes continues
(CEI 60286-3:2007)

Gurtung und Magazinierung
von Bauelementen
für die automatische Verarbeitung -
Teil 3: Gurtung von
oberflächenmontierbaren Bauelementen
auf Endlosgurten
(IEC 60286-3:2007)

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This European Standard was approved by CENELEC on 2007-09-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 40/1838/FDIS, future edition 4 of IEC 60286-3, prepared by IEC TC 40, Capacitors and resistors for electronic equipment, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60286-3 on 2007-09-01.

This European Standard supersedes EN 60286-3:1998.

EN 60286-3:2007 contains the following significant technical changes with respect to EN 60286-3:1998:

- implementation of Type IV (adhesive-backed punched plastic carrier tape for singulated bare die and other surface mount components);
- minor revisions related to tables, figures and references.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2008-06-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 2010-09-01

Annex ZA has been added by CENELEC.

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Endorsement notice

The text of the International Standard IEC 60286-3:2007 was approved by CENELEC as a European Standard without any modification.
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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60191-2	1966	Mechanical standardization of semiconductor devices - Part 2: Dimensions	-	-
IEC/TS 61340-5-1 + corr. February	1998 1999	Electrostatics - Part 5-1: Protection of electronic devices from electrostatic phenomena - General requirements	EN 61340-5-1 + corr. April	2001 2001
IEC/TS 61340-5-2	1999	Electrostatics - Part 5-2: Protection of electronic devices from electrostatic phenomena - User guide	EN 61340-5-2 + corr. August	2001 2001
IEC/TR 62258-3	2005	Semiconductor die products Part 3: Recommendations for good practice in handling, packing and storage	CLC/TR 62258-3	2007
ISO/IEC 16388	1999	Information technology - Automatic identification and data capture techniques - Bar code symbology specifications - Code 39		-
ISO 11469	2000	Plastics - Generic identification and marking of plastic products	EN ISO 11469	2000

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INTERNATIONAL STANDARD

IEC 60286-3

Fourth edition
2007-06

Packaging of components for automatic handling – Part 3: Packaging of surface mount components on continuous tapes

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Commission Electrotechnique Internationale
International Electrotechnical Commission
Международная Электротехническая Комиссия

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –**Part 3: Packaging of surface mount components
on continuous tapes**

FOREWORD

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International Standard IEC 60286-3 has been prepared by IEC technical committee 40: Capacitors and resistors for electronic equipment.

This fourth edition cancels and replaces the third edition issued in 1997. It constitutes a technical revision.

This edition contains the following significant technical changes with respect to the previous edition:

- a) implementation of Type IV (adhesive-backed punched plastic carrier tape for singulated bare die and other surface mount components);
- b) minor revisions related to tables, figures and references.

The text of this standard is based on the following documents:

FDIS	Report on voting
40/1838/FDIS	40/1847/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The list of all the parts of the IEC 60286 series, under the general title *Packaging of components for automatic handling*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date

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PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –

Part 3: Packaging of surface mount components on continuous tapes

INTRODUCTION

Tape packaging meets the requirements of automatic component placement machines and also covers the use of tape packaging for components for test purposes and other operations.

1 General

1.1 Scope

This part of IEC 60286 is applicable to the tape packaging of electronic components without leads or with lead stumps which are intended to be connected to electronic circuits. It includes only those dimensions that are essential for the taping of components intended for the above-mentioned purposes.

This standard also includes requirements related to the packaging of singulated die products including bare die and bumped die (flip chips).

1.2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191-2:1966, *Mechanical standardization of semiconductor devices – Part 2: Dimensions*

IEC 61340-5-1:1998, *Electrostatics – Part 5-1: Protection of electronic devices from electrostatic phenomena – General requirements*

IEC 61340-5-2:1999, *Electrostatics – Part 5-2: Protection of electronic devices from electrostatic phenomena – User guide*

IEC 62258-3:2005, *Semiconductor die products – Part 3: Recommendations for good practice in handling, packing and storage*

ISO/IEC 16388:1999, *Information technology – Automatic identification and data capture techniques – Bar code symbology specifications – Code 39*

ISO 11469:2000, *Plastics – Generic identification and marking of plastics products*